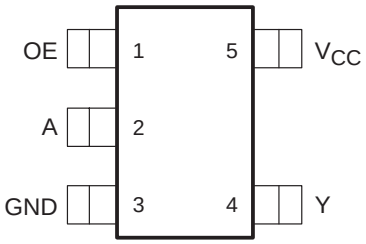
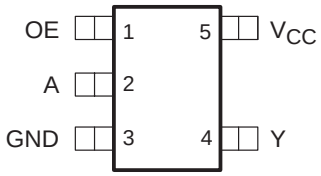
Jameco Part Number 981451

- Available in the Texas Instruments NanoStar™ and NanoFree™ Packages
- Low Static-Power Consumption (I_{CC} = 0.9 μA Max)
- Low Dynamic-Power Consumption (C_{pd} = 4 pF Typ at 3.3 V)
- Low Input Capacitance (C_i = 1.5 pF Typ)
- Low Noise − Overshoot and Undershoot <10% of V_{CC}
- Input-Disable Feature Allows Floating Input Conditions
- I_{off} Supports Partial-Power-Down Mode Operation
- Input Hysteresis Allows Slow Input Transition and Better Switching Noise Immunity at Input
- Wide Operating V_{CC} Range of 0.8 V to 3.6 V
- Optimized for 3.3-V Operation
- 3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation
- t_{pd} = 4.6 ns Max at 3.3 V
- Suitable for Point-to-Point Applications
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
  - 2000-V Human-Body Model (A114-B, Class II)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)
- ESD Protection Exceeds ±5000 V With Human-Body Model

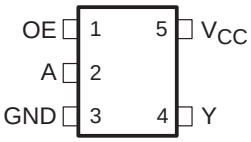
DBV PACKAGE
(TOP VIEW)



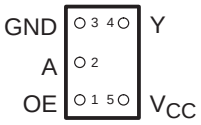
DCK PACKAGE
(TOP VIEW)



DRL PACKAGE
(TOP VIEW)



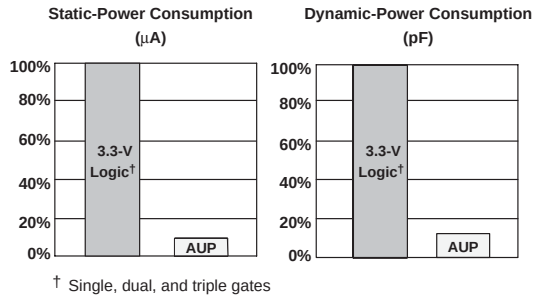
YEP OR YZP PACKAGE
(BOTTOM VIEW)



See mechanical drawings for dimensions.

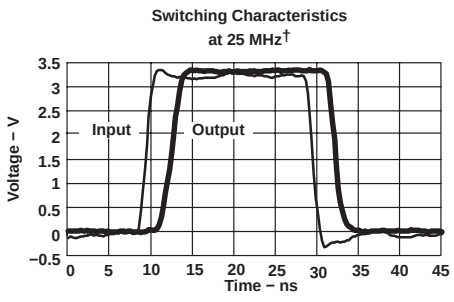
description/ordering information

The AUP family is TI's premier solution to the industry's low-power needs in battery-powered portable applications. This family ensures a very low static and dynamic power consumption across the entire V_{CC} range of 0.8 V to 3.6 V, resulting in an increased battery life. This product also maintains excellent signal integrity (see Figures 1 and 2).



† Single, dual, and triple gates

Figure 1. AUP − The Lowest-Power Family



† AUP1G08 data at C_L = 15 pF

Figure 2. Excellent Signal Integrity

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoStar and NanoFree are trademarks of Texas Instruments.

description/ordering information (continued)

This bus buffer gate is a single line driver with a 3-state output. The output is disabled when the output-enable (OE) input is low. This device has the input-disable feature, which allows floating input signals.

To ensure the high-impedance state during power up or power down, OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

NanoStar™ and NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING‡
−40°C to 85°C	NanoStar™ – WCSP (DSBGA) 0.23-mm Large Bump − YEP	Tape and reel	SN74AUP1G126YEPR	_ _ _HN_
	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump − YZP (Pb-free)	Tape and reel	SN74AUP1G126YZPR	
	SOT (SOT-23) − DBV	Tape and reel	SN74AUP1G126DBVR	H26_
	SOT (SC-70) − DCK	Tape and reel	SN74AUP1G126DCKR	HN_
	SOT (SOT-553) − DRL	Reel of 4000	SN74AUP1G126DRLR	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

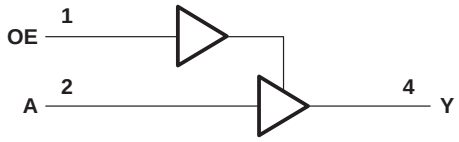
‡ DBV/DCK/DRL: The actual top-side marking has one additional character that designates the assembly/test site.
YEP/YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, ● = Pb-free).

FUNCTION TABLE

INPUTS		OUTPUT
OE	A	Y
H	H	H
H	L	L
L	X§	Z

§ Floating inputs allowed.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	−0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	−0.5 V to 4.6 V
Voltage range applied to any output in the high-impedance or power-off state, V_O (see Note 1)	−0.5 V to 4.6 V
Output voltage range in the high or low state, V_O (see Note 1)	−0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0)	−50 mA
Output clamp current, I_{OK} (V_O < 0)	−50 mA
Continuous output current, I_O	±20 mA
Continuous current through V_{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2): DBV package	206°C/W
DCK package	252°C/W
DRL package	142°C/W
YEP/YZP package	132°C/W
Storage temperature range, T_{stg}	−65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		0.8	3.6	V
V_{IH}	High-level input voltage	V_{CC} = 0.8 V	V_{CC}	3.6	V
		V_{CC} = 1.1 V to 1.95 V	$0.65 \times V_{CC}$	3.6	
		V_{CC} = 2.3 V to 2.7 V	1.6	3.6	
		V_{CC} = 3 V to 3.6 V	2	3.6	
V_{IL}	Low-level input voltage	V_{CC} = 0.8 V		0	V
		V_{CC} = 1.1 V to 1.95 V	0	$0.35 \times V_{CC}$	
		V_{CC} = 2.3 V to 2.7 V	0	0.7	
		V_{CC} = 3 V to 3.6 V	0	0.9	
V_O	Output voltage	Active state	0	V_{CC}	V
		3-state	0	3.6	
I_{OH}	High-level output current	V_{CC} = 0.8 V		−20	μA
		V_{CC} = 1.1 V		−1.1	mA
		V_{CC} = 1.4 V		−1.7	
		V_{CC} = 1.65		−1.9	
		V_{CC} = 2.3 V		−3.1	
		V_{CC} = 3 V		−4	
I_{OL}	Low-level output current	V_{CC} = 0.8 V		20	μA
		V_{CC} = 1.1 V		1.1	mA
		V_{CC} = 1.4 V		1.7	
		V_{CC} = 1.65 V		1.9	
		V_{CC} = 2.3 V		3.1	
		V_{CC} = 3 V		4	
$\Delta t/\Delta v$	Input transition rise or fall rate	V_{CC} = 0.8 V to 3.6 V		200	ns/V
T_A	Operating free-air temperature		−40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	T_A = 25°C			T_A = −40°C TO 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
V_{OH}		I_{OH} = −20 μA	0.8 V to 3.6 V	V_{CC} − 0.1			V_{CC} − 0.1		V
		I_{OH} = −1.1 mA	1.1 V	0.75 × V_{CC}			0.7 × V_{CC}		
		I_{OH} = −1.7 mA	1.4 V	1.11			1.03		
		I_{OH} = −1.9 mA	1.65 V	1.32			1.3		
		I_{OH} = −2.3 mA	2.3 V	2.05			1.97		
		I_{OH} = −3.1 mA		1.9			1.85		
		I_{OH} = −2.7 mA	3 V	2.72			2.67		
		I_{OH} = −4 mA		2.6			2.55		
V_{OL}		I_{OL} = 20 μA	0.8 V to 3.6 V			0.1		0.1	V
		I_{OL} = 1.1 mA	1.1 V			0.3 × V_{CC}		0.3 × V_{CC}	
		I_{OL} = 1.7 mA	1.4 V			0.31		0.37	
		I_{OL} = 1.9 mA	1.65 V			0.31		0.35	
		I_{OL} = 2.3 mA	2.3 V			0.31		0.33	
		I_{OL} = 3.1 mA				0.44		0.45	
		I_{OL} = 2.7 mA	3 V			0.31		0.33	
		I_{OL} = 4 mA				0.44		0.45	
I_I	A or OE input	V_I = GND to 3.6 V	0 V to 3.6 V			0.1		0.5	μA
I_{off}		V_I or V_O = 0 V to 3.6 V	0 V			0.2		0.6	μA
ΔI_{off}		V_I or V_O = 0 V to 3.6 V	0 V to 0.2 V			0.2		0.6	μA
I_{OZ}		V_O = V_{CC} or GND	3.6 V					0.5	μA
I_{CC}		V_I = GND or (V_{CC} to 3.6 V), OE = V_{CC}, I_O = 0	0.8 V to 3.6 V			0.5		0.9	μA
ΔI_{CC}	A input	V_I = V_{CC} − 0.6 V†, I_O = 0	3.3 V			40		50	μA
	OE input					110		120	
	All inputs	V_I = GND to 3.6 V, OE = GND‡	0.8 V to 3.6 V			0		0	
C_i		V_I = V_{CC} or GND	0 V		1.5				pF
			3.6 V		1.5				
C_o		V_O = V_{CC} or GND	3.6 V		3				pF

† One input at V_{CC} − 0.6 V, other input at V_{CC} or GND
‡ To show I_{CC} is very low when the input-disable feature is enabled

switching characteristics over recommended operating free-air temperature range, C_L = 5 pF (unless otherwise noted) (see Figures 3 and 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = 25°C			T_A = −40°C TO 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A	Y	0.8 V		18.1				ns
			1.2 V ± 0.1 V	4.3	7.4	12.6	2.7	15.3	
			1.5 V ± 0.1 V	3.3	5.2	8.5	1	10.2	
			1.8 V ± 0.15 V	2.6	4.1	6.8	1.3	8.3	
			2.5 V ± 0.2 V	2	2.9	4.7	1.1	5.8	
			3.3 V ± 0.3 V	1.7	2.4	3.8	1	4.6	
t_{en}	OE	Y	0.8 V		19.1				ns
			1.2 V ± 0.1 V	5.1	9.3	15.9	3.6	19.2	
			1.5 V ± 0.1 V	4.1	6.6	10.5	2.5	12.7	
			1.8 V ± 0.15 V	3.2	5.3	8.7	2.1	10.3	
			2.5 V ± 0.2 V	2.5	3.8	6	1.6	7.2	
			3.3 V ± 0.3 V	2.1	3.2	4.9	1.4	5.9	
t_{dis}	OE	Y	0.8 V		12.1				ns
			1.2 V ± 0.1 V	2.4	4.1	6.9	2.2	7.7	
			1.5 V ± 0.1 V	1.8	2.9	4.5	1.7	5.1	
			1.8 V ± 0.15 V	1	2.9	4.3	1.5	4.7	
			2.5 V ± 0.2 V	1	1.8	2.7	1	3.3	
			3.3 V ± 0.3 V	1.2	2.2	3.2	1.1	4	

switching characteristics over recommended operating free-air temperature range, C_L = 10 pF (unless otherwise noted) (see Figures 3 and 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = 25°C			T_A = −40°C TO 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A or B	Y	0.8 V		20.5				ns
			1.2 V ± 0.1 V	4.6	8.4	13.7	3.6	16.6	
			1.5 V ± 0.1 V	3.5	5.9	9.3	2.4	11.1	
			1.8 V ± 0.15 V	3.9	4.7	7.5	1.3	9.1	
			2.5 V ± 0.2 V	2.3	3.4	5.3	1.6	6.4	
			3.3 V ± 0.3 V	2.1	2.8	4.3	1.4	5.2	
t_{en}	OE	Y	0.8 V		21.8				ns
			1.2 V ± 0.1 V	4.9	10.2	16.8	4.4	20.2	
			1.5 V ± 0.1 V	3.9	7.3	11.2	3.3	13.5	
			1.8 V ± 0.15 V	3.4	5.8	9.2	2.7	11	
			2.5 V ± 0.2 V	2.5	4.3	6.4	2.1	7.8	
			3.3 V ± 0.3 V	2.1	3.7	5.4	1.9	6.4	
t_{dis}	OE	Y	0.8 V		13				ns
			1.2 V ± 0.1 V	3.8	6.6	11.7	1.2	14	
			1.5 V ± 0.1 V	2.2	4.7	7.9	1.3	9.3	
			1.8 V ± 0.15 V	2.4	4.4	6.4	2.2	7.5	
			2.5 V ± 0.2 V	1.3	3.1	4.9	1.2	5.4	
			3.3 V ± 0.3 V	1.9	3.4	5	1.9	5.6	

switching characteristics over recommended operating free-air temperature range, C_L = 15 pF (unless otherwise noted) (see Figures 3 and 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = 25°C			T_A = −40°C TO 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A or B	Y	0.8 V		22.5				ns
			1.2 V ± 0.1 V	5.8	9.3	15.1	4.3	17.9	
			1.5 V ± 0.1 V	4.4	6.6	10.2	3	12.1	
			1.8 V ± 0.15 V	3.5	5.3	8.3	2.3	9.9	
			2.5 V ± 0.2 V	2.7	3.9	5.8	1.9	7	
			3.3 V ± 0.3 V	2.4	3.2	4.7	1.8	5.7	
t_{en}	OE	Y	0.8 V		25.2				ns
			1.2 V ± 0.1 V	7	11.3	18.1	5.4	21.4	
			1.5 V ± 0.1 V	5.5	8.1	12.2	4.1	14.5	
			1.8 V ± 0.15 V	4.3	6.5	10.1	3.3	12	
			2.5 V ± 0.2 V	3.4	4.8	7.1	2.6	8.4	
			3.3 V ± 0.3 V	2.9	4.1	5.9	2.3	6.9	
t_{dis}	OE	Y	0.8 V		14				ns
			1.2 V ± 0.1 V	3.7	5.8	8.2	3.3	11	
			1.5 V ± 0.1 V	5.5	3.9	5.9	2.1	8	
			1.8 V ± 0.15 V	3.3	4.5	6.6	2.9	7.4	
			2.5 V ± 0.2 V	2.3	3.2	4.3	1.8	5.1	
			3.3 V ± 0.3 V	2.4	4.8	6.2	3.1	6.7	

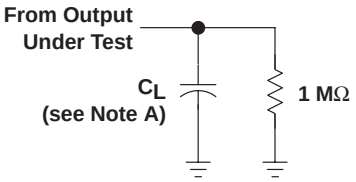
switching characteristics over recommended operating free-air temperature range, C_L = 30 pF (unless otherwise noted) (see Figures 3 and 4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = 25°C			T_A = −40°C TO 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A or B	Y	0.8 V		29				ns
			1.2 V ± 0.1 V	7.4	12	18.7	6.6	21.4	
			1.5 V ± 0.1 V	5.7	8.6	12.5	4.9	14.7	
			1.8 V ± 0.15 V	4.8	6.9	10.1	3.1	12	
			2.5 V ± 0.2 V	3.9	5.1	7.2	3.3	8.7	
			3.3 V ± 0.3 V	3.5	4.8	6	3	7	
t_{en}	OE	Y	0.8 V		33.4				ns
			1.2 V ± 0.1 V	8.8	14.1	21.8	7.4	25.5	
			1.5 V ± 0.1 V	6.9	10.1	14.6	5.6	17.4	
			1.8 V ± 0.15 V	5.6	8.1	12	4.7	14.1	
			2.5 V ± 0.2 V	4.3	6.1	8.5	3.8	10	
			3.3 V ± 0.3 V	3.7	5.2	7.1	3.4	8.3	
t_{dis}	OE	Y	0.8 V		17.7				ns
			1.2 V ± 0.1 V	5.8	10	16	3.7	16	
			1.5 V ± 0.1 V	5.7	7.7	10.9	1	10.7	
			1.8 V ± 0.15 V	4.5	7.7	9.8	4.4	12.5	
			2.5 V ± 0.2 V	3.9	5.6	7.4	3.2	9	
			3.3 V ± 0.3 V	3.3	8.4	10.7	6.6	10.8	

operating characteristics, T_A = 25°C

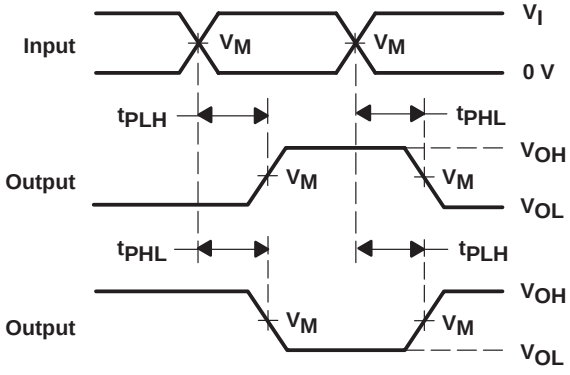
PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd} Power dissipation capacitance	Outputs enabled	f = 10 MHz	0.8 V	3.8	pF
			1.2 V ± 0.1 V	3.7	
			1.5 V ± 0.1 V	3.7	
			1.8 V ± 0.15 V	3.7	
			2.5 V ± 0.2 V	3.9	
			3.3 V ± 0.3 V	4	
	Outputs disabled	f = 10 MHz	0.8 V	0	
			1.2 V ± 0.1 V	0	
			1.5 V ± 0.1 V	0	
			1.8 V ± 0.15 V	0	
			2.5 V ± 0.2 V	0	
			3.3 V ± 0.3 V	0	

PARAMETER MEASUREMENT INFORMATION
(Propagation Delays, Setup and Hold Times, and Pulse Width)

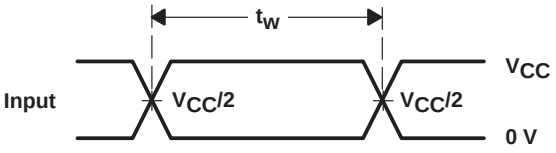


LOAD CIRCUIT

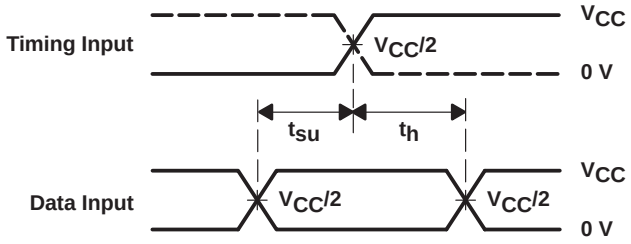
	V_{CC} = 0.8 V	V_{CC} = 1.2 V ± 0.1 V	V_{CC} = 1.5 V ± 0.1 V	V_{CC} = 1.8 V ± 0.15 V	V_{CC} = 2.5 V ± 0.2 V	V_{CC} = 3.3 V ± 0.3 V
C_L	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V_M	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
V_I	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
PULSE DURATION

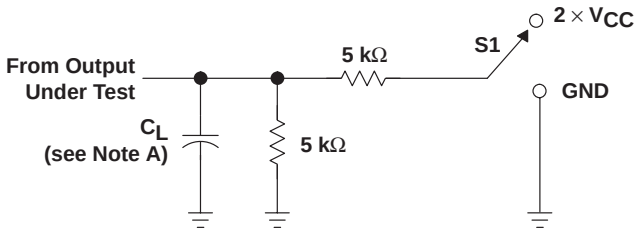


VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r/t_f = 3 ns.
C. The outputs are measured one at a time, with one transition per measurement.
D. t_{PLH} and t_{PHL} are the same as t_{pd}.
E. All parameters and waveforms are not applicable to all devices.

Figure 3. Load Circuit and Voltage Waveforms

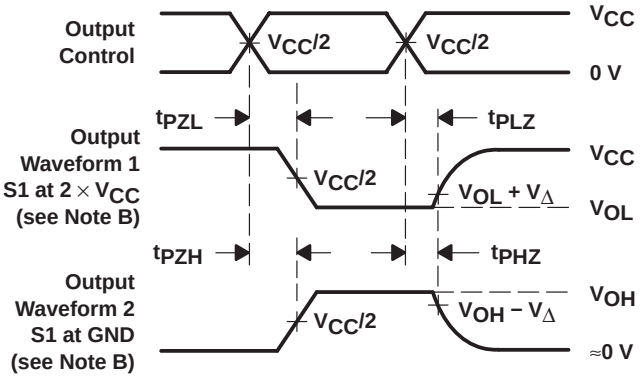
PARAMETER MEASUREMENT INFORMATION
(Enable and Disable Times)



LOAD CIRCUIT

TEST	S1
t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	$2 \times V_{CC}$ GND

	V_{CC} = 0.8 V	V_{CC} = 1.2 V ± 0.1 V	V_{CC} = 1.5 V ± 0.1 V	V_{CC} = 1.8 V ± 0.15 V	V_{CC} = 2.5 V ± 0.2 V	V_{CC} = 3.3 V ± 0.3 V
C_L	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V_M	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
V_I	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}
V_Δ	0.1 V	0.1 V	0.1 V	0.15 V	0.15 V	0.3 V



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r/t_f = 3 ns.
D. The outputs are measured one at a time, with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. All parameters and waveforms are not applicable to all devices.

Figure 4. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
74AUP1G126DBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AUP1G126DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AUP1G126DBVTE4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AUP1G126DBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AUP1G126DCKRE4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AUP1G126DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AUP1G126DCKTE4	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AUP1G126DCKTG4	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AUP1G126DRLRG4	ACTIVE	SOT-553	DRL	5	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G126DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G126DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G126DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G126DCKT	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G126DRLR	ACTIVE	SOT-553	DRL	5	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AUP1G126YZPR	ACTIVE	WCSP	YZP	5	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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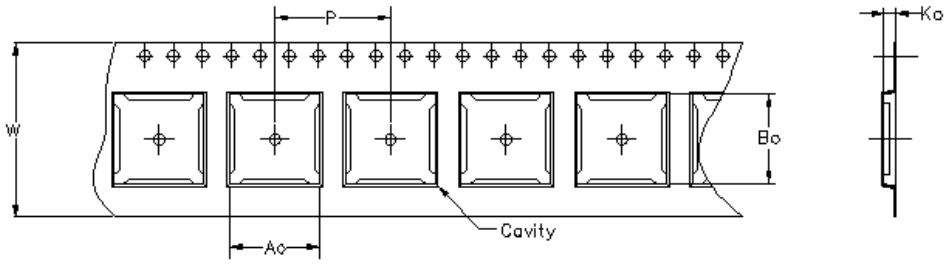
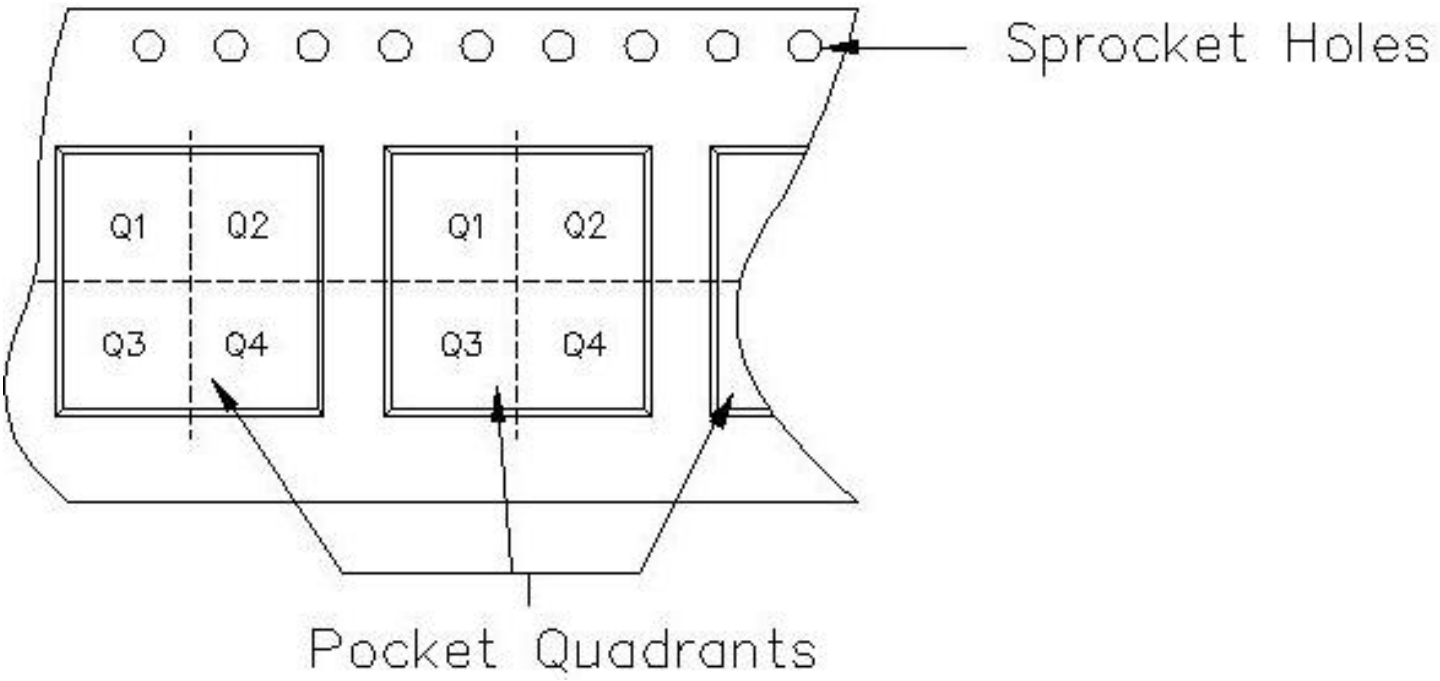


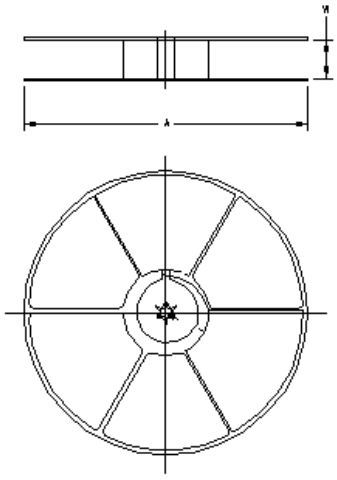
Carrier tape design is defined largely by the component lentgh, width, and thickness.

Ao = Dimension designed to accommodate the component width.
Bo = Dimension designed to accommodate the component length.
Ko = Dimension designed to accommodate the component thickness.
W = Overall width of the carrier tape.
P = Pitch between successive cavity centers.



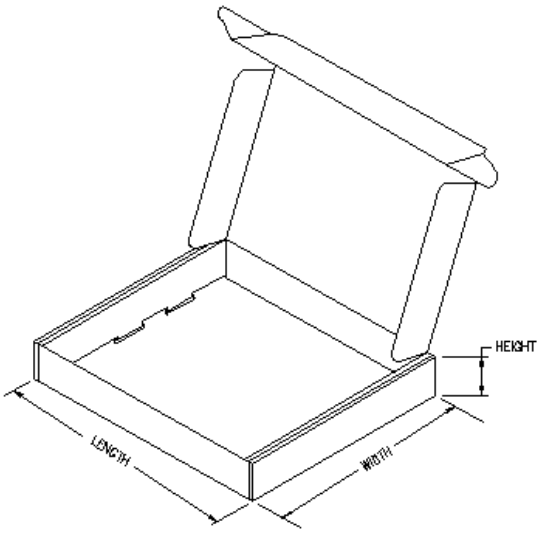
TAPE AND REEL INFORMATION

Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AUP1G126DBVR	DBV	5	HNT	180	9	3.23	3.17	1.37	4	8	Q3
SN74AUP1G126DBVT	DBV	5	HNT	180	9	3.23	3.17	1.37	4	8	Q3
SN74AUP1G126DCKR	DCK	5	HNT	180	9	2.24	2.34	1.22	4	8	Q3
SN74AUP1G126DCKT	DCK	5	HNT	180	9	2.24	2.34	1.22	4	8	Q3
SN74AUP1G126DRLR	DRL	5	HNT	180	9	1.78	1.78	0.69	4	8	Q3
SN74AUP1G126YZPR	YZP	5	ASEK	180	8	1.02	1.52	0.66	4	8	Q1

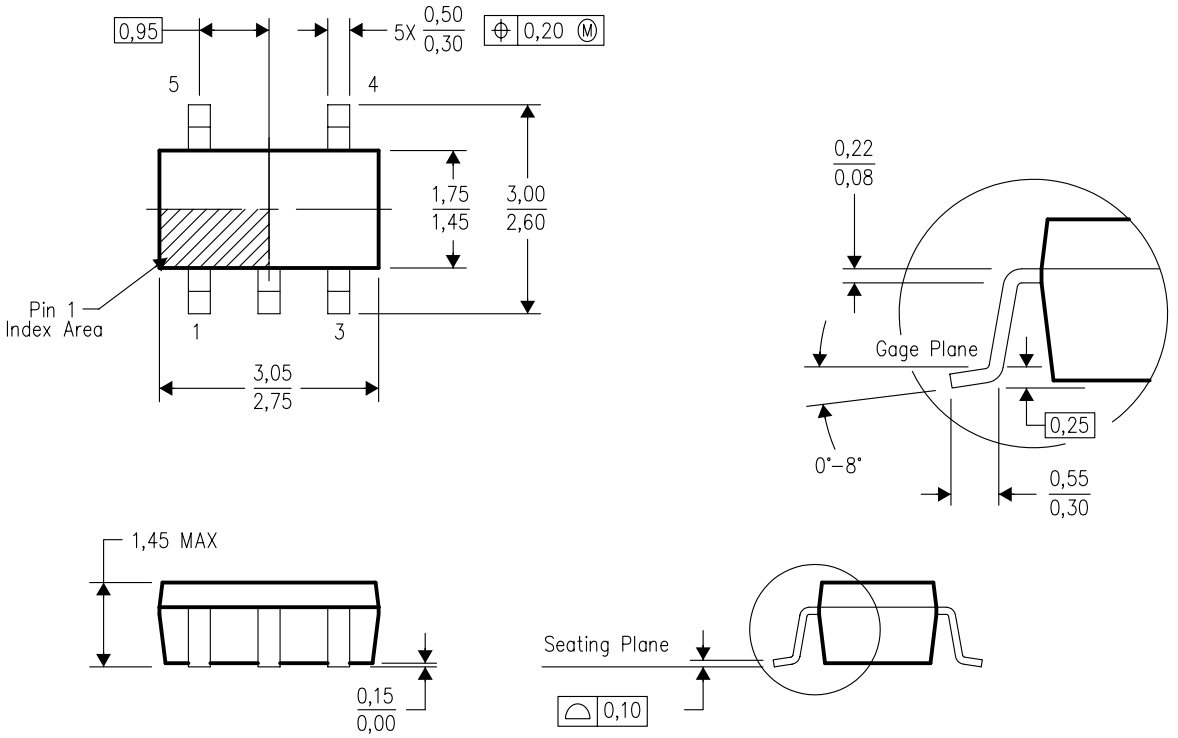


TAPE AND REEL BOX INFORMATION

Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74AUP1G126DBVR	DBV	5	HNT	202.0	201.0	28.0
SN74AUP1G126DBVT	DBV	5	HNT	202.0	201.0	28.0
SN74AUP1G126DCKR	DCK	5	HNT	202.0	201.0	28.0
SN74AUP1G126DCKT	DCK	5	HNT	202.0	201.0	28.0
SN74AUP1G126DRLR	DRL	5	HNT	202.0	201.0	28.0
SN74AUP1G126YZPR	YZP	5	ASEK	220.0	220.0	34.0


HEIGHT
LENGTH
WIDTH

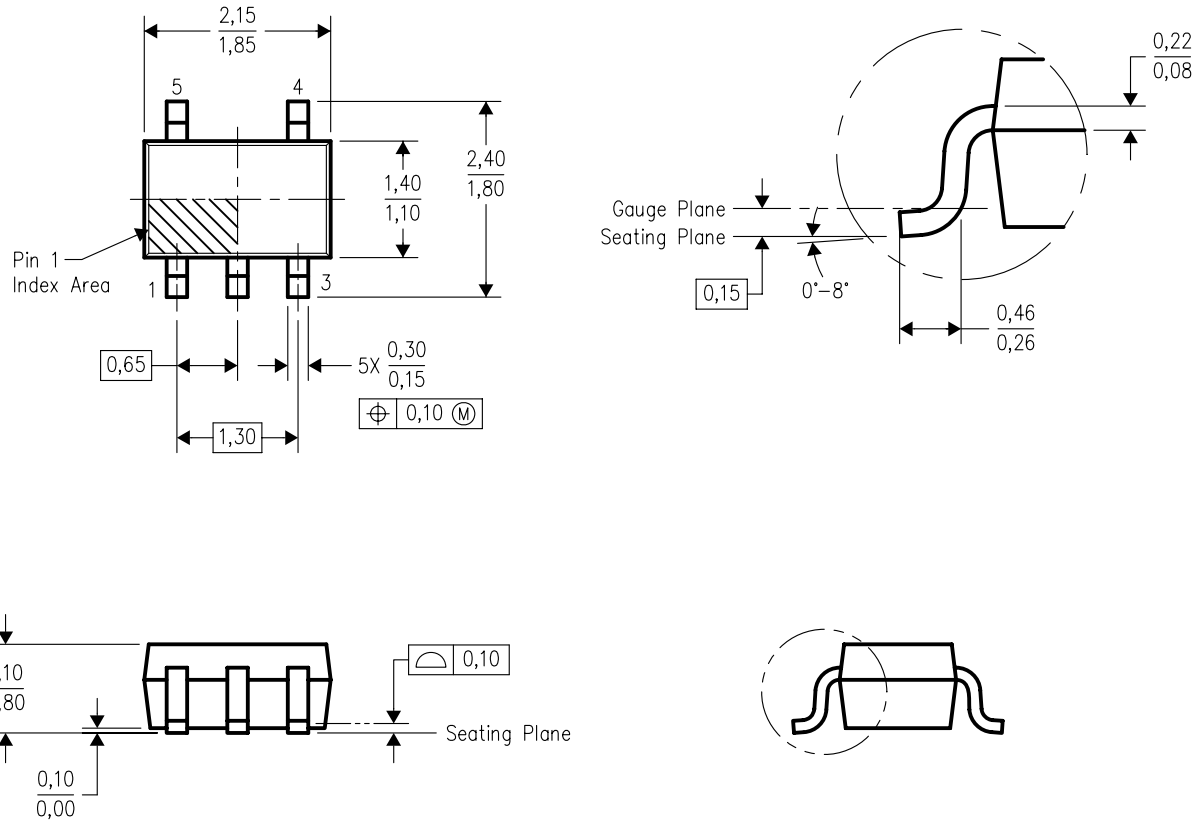
DBV (R–PDSO–G5) PLASTIC SMALL–OUTLINE PACKAGE



4073253–4/K 03/2006

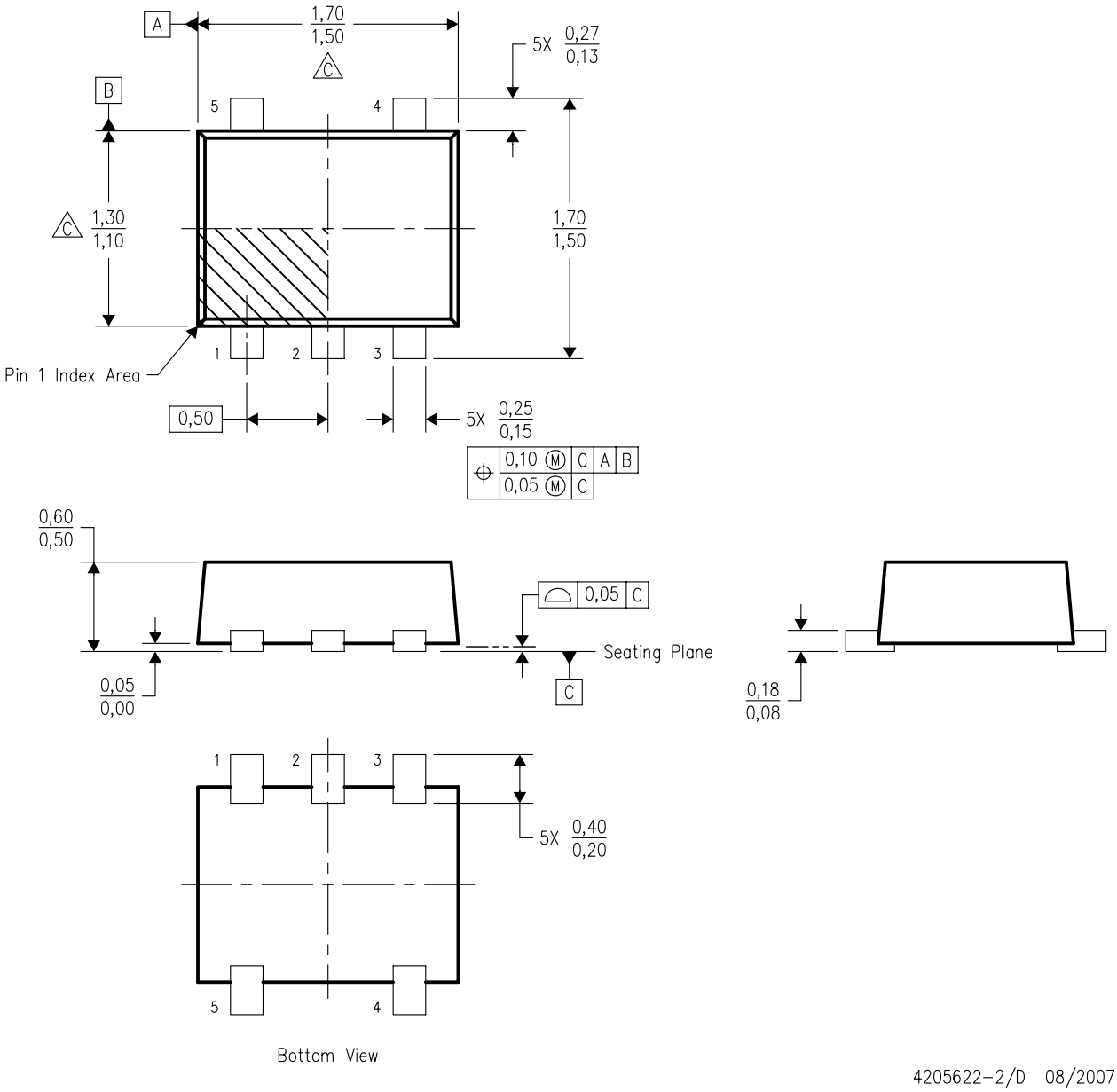
NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
D. Falls within JEDEC MO–178 Variation AA.

DCK (R–PDSO–G5) PLASTIC SMALL–OUTLINE PACKAGE



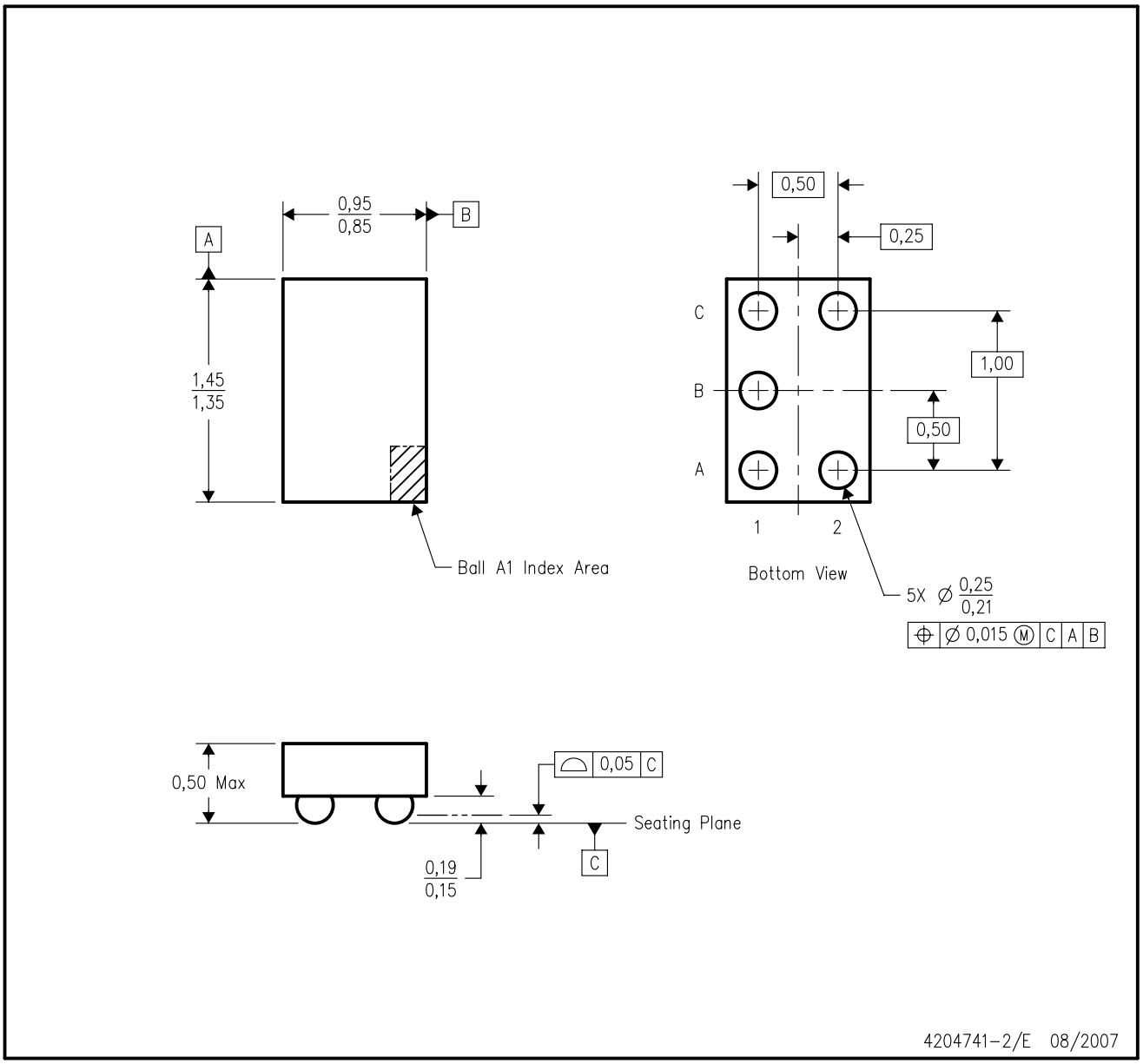
4093553–3/G 01/2007

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
D. Falls within JEDEC MO–203 variation AA.



NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash, interlead flash, protrusions, or gate burrs. Mold flash, interlead flash, protrusions, or gate burrs shall not exceed 0,15 per end or side.
D. JEDEC package registration is pending.

YZP (R–XBGA–N5) DIE–SIZE BALL GRID ARRAY



NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. NanoFree™ package configuration.
D. This package is lead–free. Refer to the 5 YEP package (drawing 4204725) for tin–lead (SnPb).

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